Specifications

Insulation Resistance: 1000MΩ min.
Current Rating: 1A max. per contact
Voltage Rating: 30V AC (rms) max.
Withstanding Voltage: 750V AC
Contact Resistance: 15mΩ max. (initial)
Operating Temperature Range: -55°C to + 85°C
Soldering Temperature: 250°C min. / 3 sec.
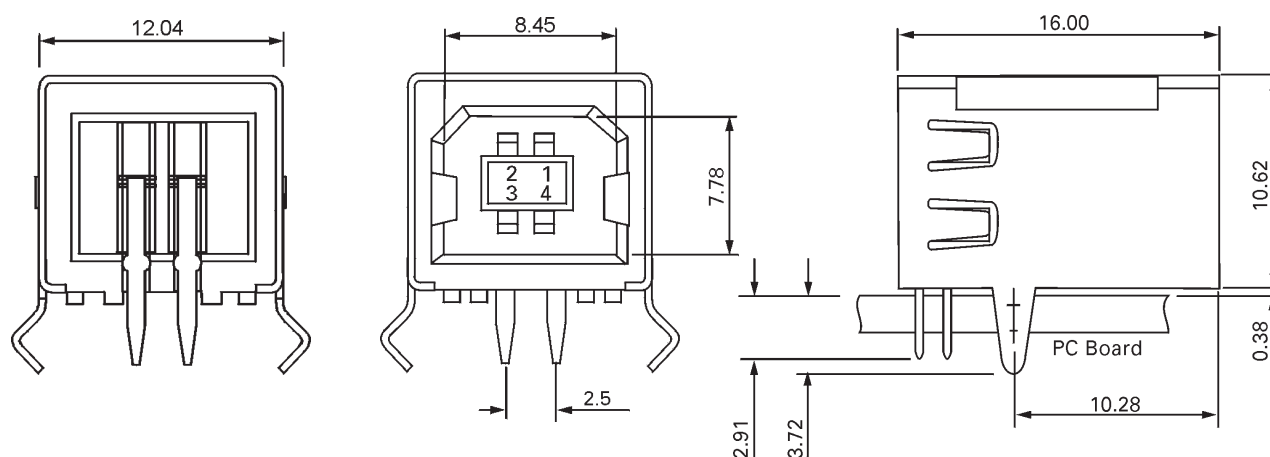
Part Number

USB-B-001

*USB-B-001-30
* see Materials and Finish

Materials and Finish
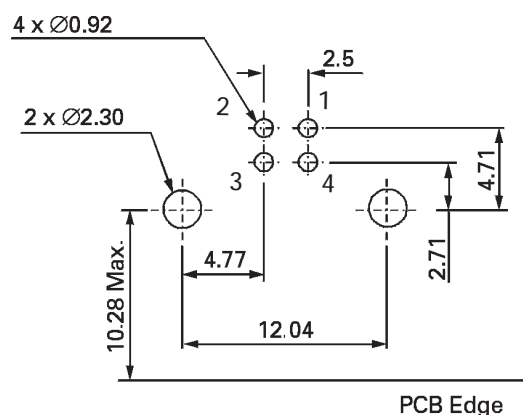
Housing: PBT, glass filled (UL94V-0)
Shell: Copper Alloy, CuNi plating
Contacts: Copper Alloy
Contact Plating: Solder Terminal - Sn over Ni
                  Mating Area   - USB-B-001 = Au Flash over Ni
                                 - USB-B-001-30 = 30µ" Au over Ni

✔RoHS

TH Type

Recommended PCB Layout

Top View

4 x ∅0.92

2.5

2 x ∅2.30

4.71

10.28 Max.

4.77

2.71

12.04

PCB Edge

Specifications

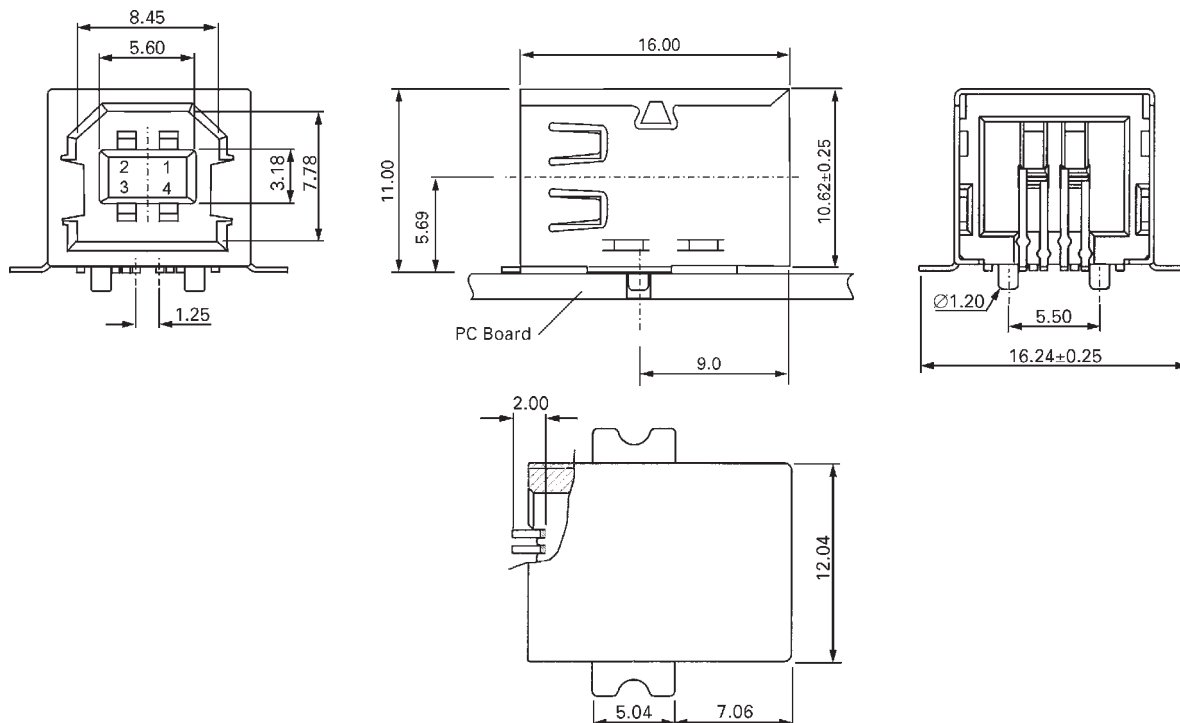|	
Insulation Resistance:	1000MΩ min.
Current Rating:	1A max. per contact
Voltage Rating:	30V AC (rms) max.
Withstanding Voltage:	500V AC
Contact Resistance:	30mΩ max. (initial)
Operating Temperature Range:	-55°C to + 85°C
Soldering Temperature:	220°C min. / 60 secs, 250°C peak

Materials and Finish

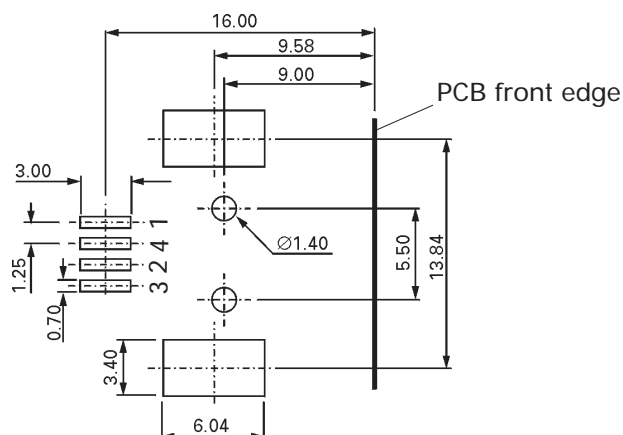|	
Housing:	Thermoplastic, glass filled (UL94V-0)
Shell:	Copper Alloy, bright Tin over Cu
Contacts:	Copper Alloy
Contact Plating:	Solder Area - SnCu over Ni
	Mating Area - 30µ" Au over Ni

✔ RoHS

Part Number

USB-B-003

90° SMT Type

Recommended PCB Layout

Top View

PCB front edge

YAMAICHI ELECTRONICS
Trading Division

Specifications

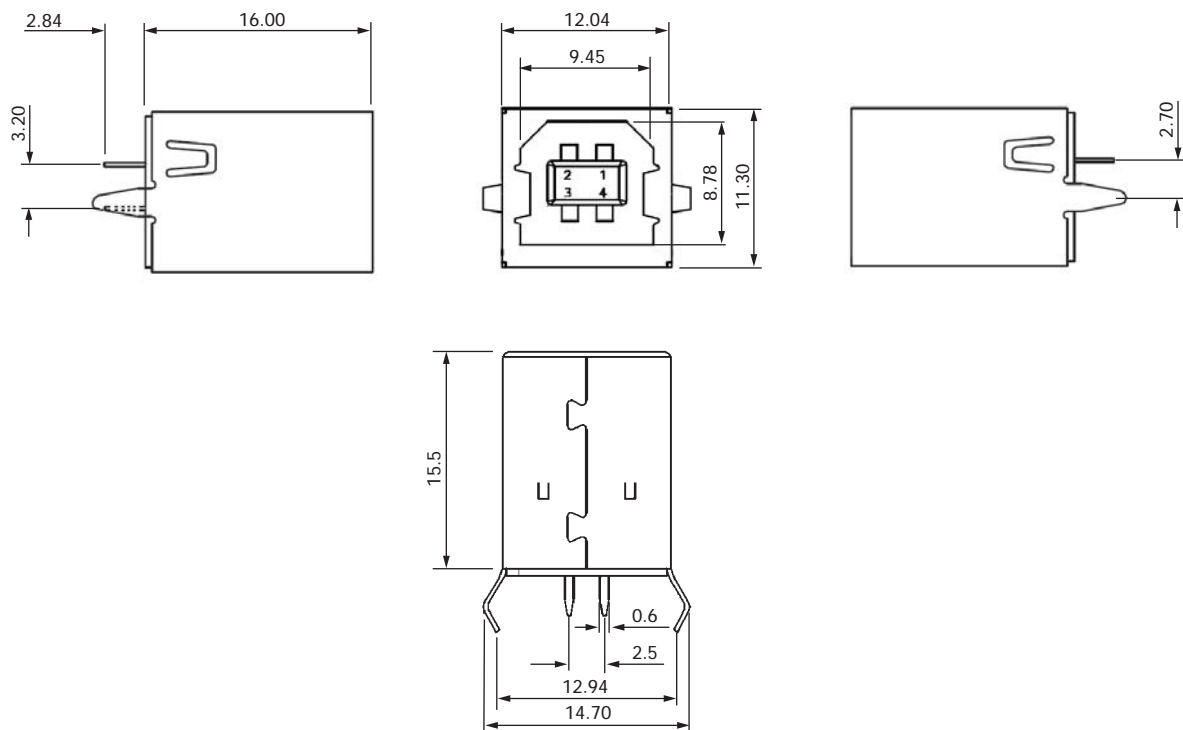|	
Insulation Resistance:	1000MΩ min.
Current Rating:	1.5A max. per contact
Voltage Rating:	30V AC (rms) max.
Withstanding Voltage:	500V AC
Contact Resistance:	30mΩ max. (initial)
Operating Temperature Range:	-55°C to + 85°C
Soldering Temperature:	250°C / 3 sec.

Part Number

USB-B-004

*USB-B-004-30

* see Materials and Finish

Materials and Finish

Housing:	PBT, glass filled (UL94V-0)
Shell:	Copper Alloy, Ni plating
Contacts:	Copper Alloy
Contact Plating:	Solder Terminal - Sn over Ni
	Mating Area - USB-B-004 = Au Flash over Ni
	- USB-B-004-30 = 30µ" Au over Ni

✔ RoHS

180° - TH Type

Recommended PCB Layout

Top View